

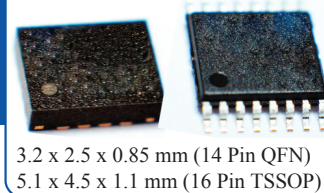
CRYSTAL-LESS PCI EXPRESS DUAL OUTPUT ULTRA MINIATURE PURE SILICON™ SMD CLOCK GENERATOR

AB-557-03 Series

Moisture Sensitivity Level
MSL 1 – 14 QFN
MSL 3 – 16 TSSOP



RoHS/RoHS II compliant



3.2 x 2.5 x 0.85 mm (14 Pin QFN)
5.1 x 4.5 x 1.1 mm (16 Pin TSSOP)

FEATURES:

- Meets PCIe Gen1, Gen2, & Gen3 specs.
- High Performance MEMS Technology by Discera
- Available Mixed Output Formats: HCSL, LVPECL, LVDS or LVCMOS
- Wide Temperature Range: -40° to 105° C
- Wide Supply Range: 2.25V to 3.6 V
- Low Power Consumption
- Excellent Shock & Vibration Immunity

APPLICATIONS:

- Solid State Storage
- Storage Area Networks
- Passive Optical Networks
- Ethernet: 1G, 10GBASE-T/KR/LR/SR, and FCoE
- TV and other Consumer Electronics
- Industrial and Medical
- Scanner, Printer

STANDARD SPECIFICATIONS:

Parameters		Minimum	Typical	Maximum	Unite	Notes
Frequency	f ₀	2.3	100	460 ^{*1}	MHz	
Operating Temperature		-20		+70	°C	See options
Storage Temperature		-55		+150	°C	
Overall Freq. Stability ^{*2}	Δf	-100		+100	ppm	See options
Supply Voltage	V _{DD}	+2.25		+3.6	V	
Supply Current- Enabled	I _{DD}		60		mA	R _L =50Ω, F ₀₁ =F ₀₂ =100.00MHz
Supply Current- Disabled	I _{DD}		21	23	mA	
Startup Time	t _{su}			5	ms	
Enable Time	t _{EN}			20	ns	
Disable Time	t _{DA}			5	ns	
Tri-state Function (Standby/Disable)		"1" (VIH≥0.75*Vdd) or Open: Oscillation "0" (VIL<0.25*Vdd) : Hi Z			V	40kΩ pull-up resistor embedded
Aging		-5.0		+5.0	ppm	First year
Output Offset Voltage	V _{OH} V _{OL}	0.725		0.10	V	R _L =50 Ω
Peak to Peak Output Swing			750		mV	Single-Ended
Rise Time	t _r	200		400	ps	R _L =50 Ω, C _L =2pF
Fall Time	t _f	200		400	ps	20% to 80%
Duty Cycle	SYM	48		52	%	Differential
Period Jitter	J _{PER}		2.5		ps _{RMS}	F ₀₁ =F ₀₂ =100.00MHz
Integrated Phase Noise (Common Clock Architecture)	R _J		0.540		ps _{RMS}	PCIe Gen 1.1 T _J = D _J + 14.069 x R _J (BER 10-12)
	D _J		0.832	41.9	ps _{p-p}	
	T _J		8.536	86.0		
	J _{RMS-CCHF}		0.458	3.1	ps _{RMS}	PCIe Gen 2.1 1.5 MHz to Nyquist
	J _{RMS-CCLF}		0.030	3.0		PCIe Gen 2.1 10kHz to 1.5 MHz
	J _{RMS-CC}		0.165	1.0	ps _{RMS}	PCIe Gen 3.0
Integrated Phase Noise (Data Clock Architecture)	J _{RMS-DCHF}		0.561	4.0	ps _{RMS}	PCIe Gen 2.1 1.5 MHz to Nyquist
	J _{RMS-DCLF}		1.778	7.5		PCIe Gen 2.1 10kHz to 1.5 MHz
	J _{RMS-DC}		0.147	1.0	ps _{RMS}	PCIe Gen 3.0

*1. For frequency other than 100MHz, please contact ABRACON or consider using ASEMDxx series

2. Frequency stability includes frequency variations due to initial tolerance, temp. and power supply voltage

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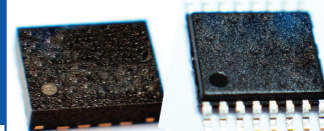
Revised: 04.12.13

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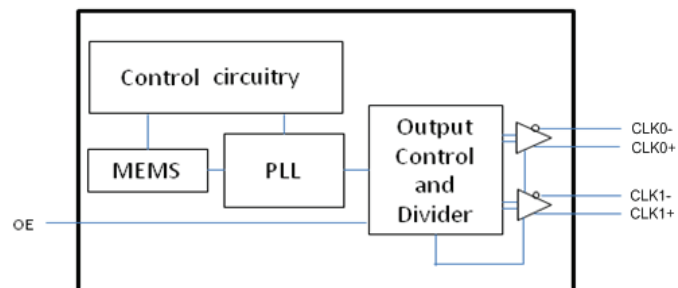


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5.1 x 4.5 x 1.1 mm (16 Pin TSSOP)

Absolute Maximum Ratings

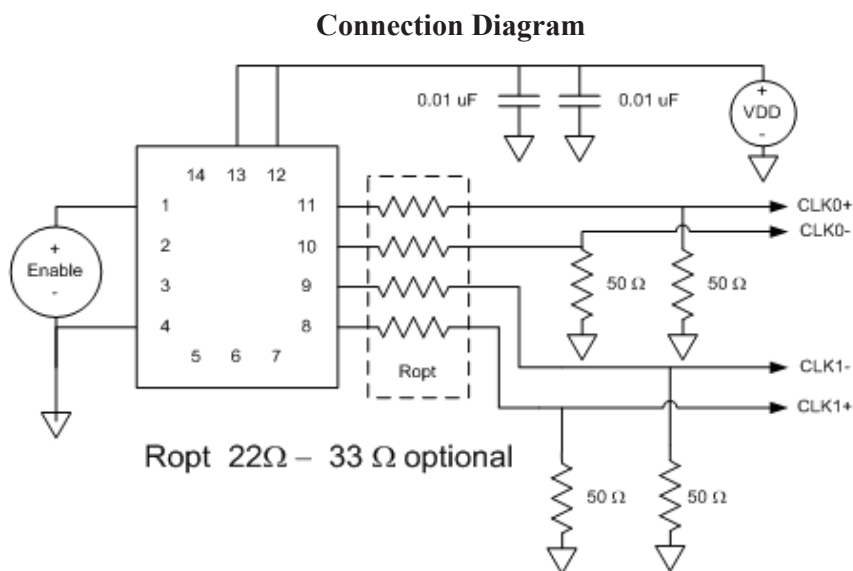
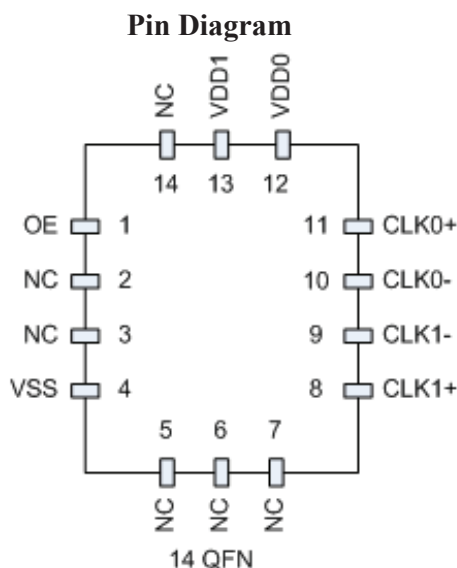
Item	Minimum	Maximum	Unit	Condition
Supply Voltage	-0.3	+4.0	V	
Input Voltage	-0.3	$V_{dd}+0.3$	V	
Junction Temp.		+150	°C	
Storage Temp.	-55	+150	°C	
Soldering Temp.		+260	°C	40sec max
ESD				
HBM		4,000	V	
MM		400		
CDM		1,500		

Block Diagram:



PIN LAYOUT:

14 Pin QFN:



Pin No.	Pin Name	Pin Type	Description
1	OE	I	Output Enable; active high
2	NC	NA	Ground Connected or Leave Unconnected
3	NC	NA	Ground Connected or Leave Unconnected
4	VSS	Power	Ground
5	NC	NA	Ground Connected or Leave Unconnected
6	NC	NA	Ground Connected or Leave Unconnected
7	NC	NA	Ground Connected or Leave Unconnected
8	CLK1+	O	True output of differential pair
9	CLK1-	O	Complement output of differential pair
10	CLK0-	O	Complement output of differential pair
11	CLK0+	O	True output of differential pair
12	VDD0	Power	Power Supply for Output 0 (CLK+/- 0)
13	VDD1	Power	Power Supply for Core and Output 1 (CLK +/- 1)
14	NC	NA	Ground Connected or Leave Unconnected

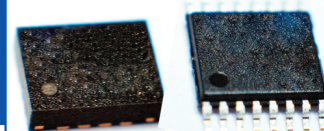


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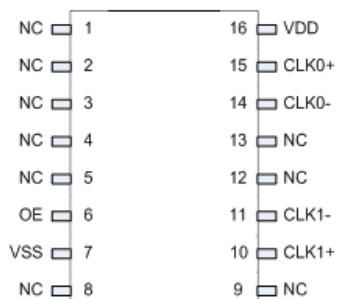
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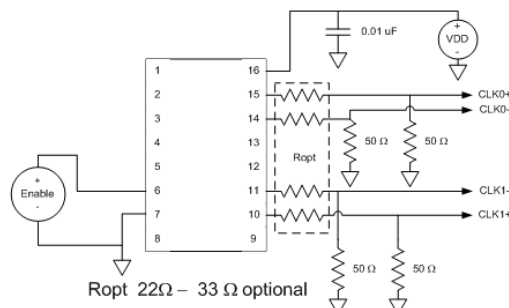
16 Pin TSSOP:

Pin Diagram



16-pin TSSOP

Connection Diagram



Pin No.	Pin Name	Pin Type	Description
1	NC	NA	Leave Unconnected
2	NC	NA	Leave Unconnected
3	NC	NA	Leave Unconnected
4	NC	NA	Leave Unconnected
5	NC	NA	Leave Unconnected
6	OE	I	Output Enable; active high
7	VSS	Power	Ground
8	NC	NA	Leave Unconnected
9	NC	NA	Leave Unconnected
10	CLK1+	O	True output of differential pair
11	CLK1-	O	Complement output of differential pair
12	NC	NA	Leave Unconnected
13	NC	NA	Leave Unconnected
14	CLK0-	O	Complement output of differential pair
15	CLK0+	O	True output of differential pair
16	VDD	Power	Power Supply

PART IDENTIFICATION:

AB-557-03-□□-□-□-□-□

Output Format, Clk1
C: LVCMOS
LP: LVPECL
LV: LVDS
HC: HCSL

Output Format, Clk0
C: LVCMOS
LP: LVPECL
LV: LVDS
HC: HCSL

Package Type
F: 14-QFN
S: 16-TSSOP

Operating Temp.
E: -20°C ~ +70°C
L: -40°C ~ +85°C
X: -40°C ~ +105°C

Overall Freq. Stability
Blank: ±100ppm
C: ±50ppm

Packaging
Blank: Bulk
T: Tape & Reel(1kpcs / reel)
T3: Tape & Reel(3kpcs/reel)

Note: For frequency other than 100MHz, please contact ABRACON or consider using ASEMDxx series

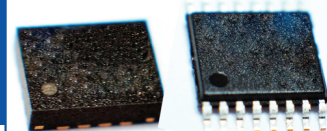


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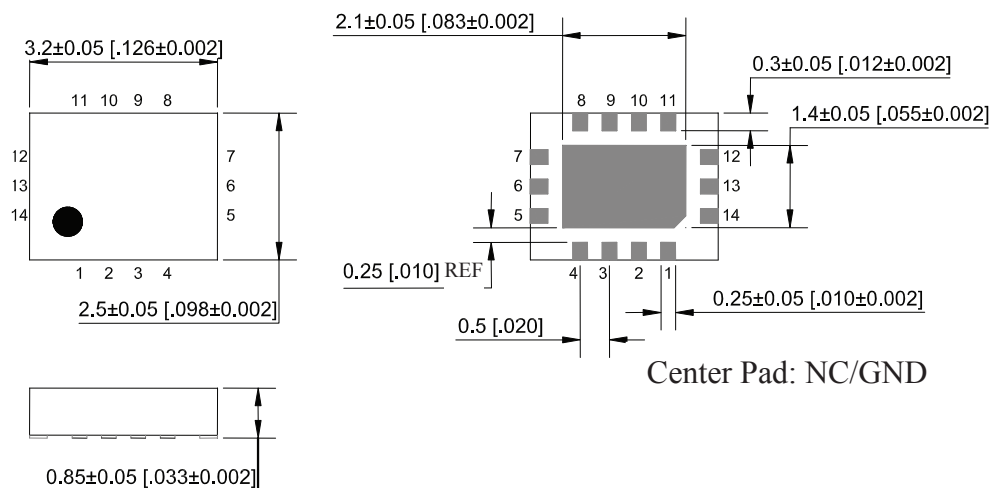
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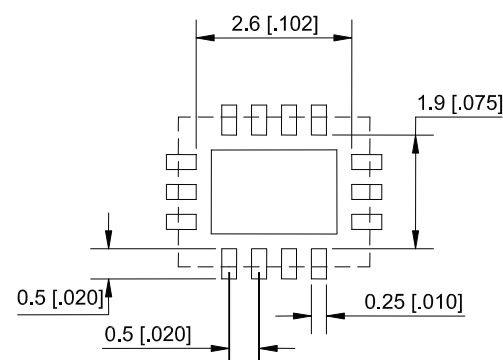
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OUTLINE DRAWING:

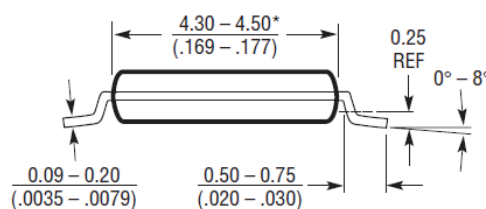
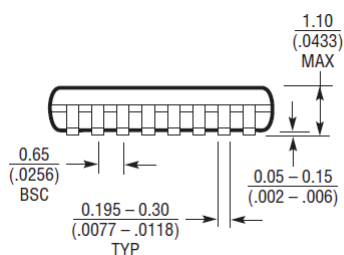
14 Pin QFN:



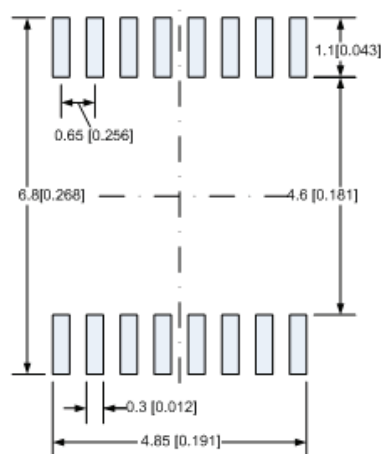
Recommended Solder Pad Layout



16 Pin TSSOP:



Recommended Solder Pad Layout



* Dimensions do not include mold flash. Mold flash shall not exceed 0.150mm (.006 inches) per side.

Dimensions: mm (inches)

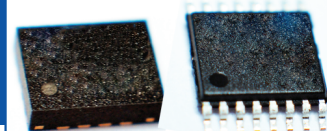


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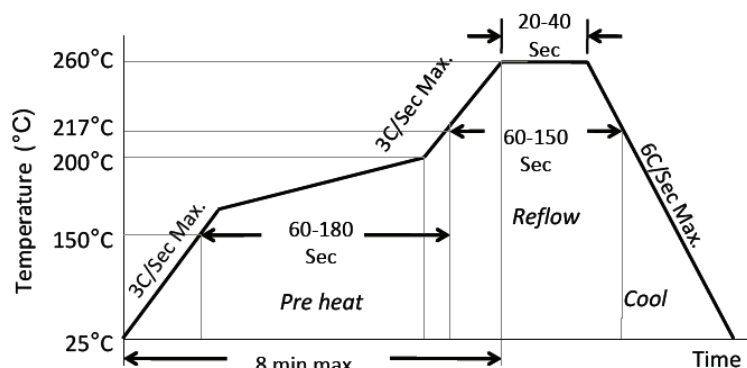


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REFLOW PROFILE:

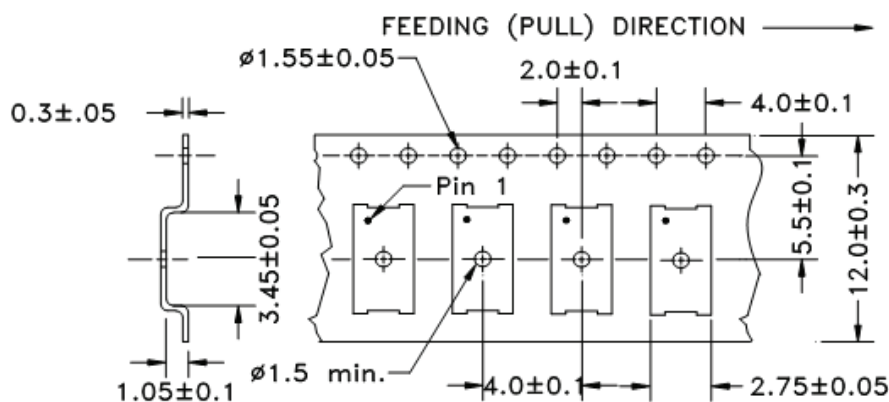


Ramp-Up Rate (200°C to Peak Temp)	3°C/Sec Max.
Preheat Time 150°C to 200°C	60-180 Sec
Time maintained above 217°C	60-150 Sec
Peak Temperature	255-260°C
Time within 5°C of actual Peak	20-40 Sec
Ramp-Down Rate	6°C/Sec Max.
Time 25°C to Peak Temperature	8 min Max.

TAPE & REEL:

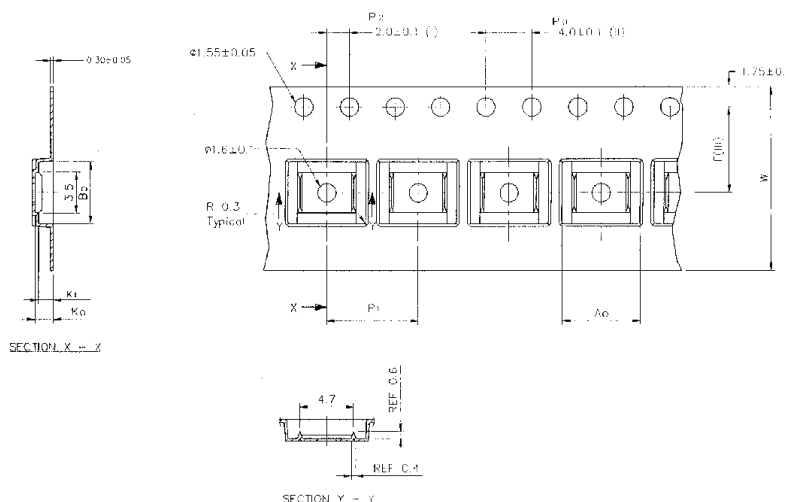
14 Pin QFN Tape Drawing:

T= 1,000pcs/reel
T3= 3,000pcs/reel



16 Pin TSSOP Tape Drawing

T= 1,000pcs/reel
T3= 3,000pcs/reel



A0	B0	K0	K1	F	P1	W
6.80±0.1	5.40±0.1	1.60±0.1	1.30±0.1	5.50±0.1	8.00±0.1	12.00±0.3

Dimensions: mm





3.2 x 2.5 x 0.85 mm (14 Pin QFN)
5.1 x 4.5 x 1.1 mm (16 Pin TSSOP)

12.0 mm. x 0.3 mm. THICK.

EMBOSSED LINE (2x)
1.5"±0.012" THICK

DETAIL "X"

W3
112.35 ± 15.4
W1 112.4 ± 0.2
0.0

0.05 (MIN)

Q 17.9 ± 0.3
Q 54.5 ± 0.5
W2
18.4" MAX

EMBOSSED LETTER "MPN"
16.0 mm HEIGHT x MIN 0.4 mm. THICK

12.0

24.7

45.0

62.0

10.0

1.0

12MM

SLOT 5.0 ± 0.5 (2x)
WIDTH of HUB

EMBOSSED LINE THICKNESS 0.4 mm
REFERENCE TO CENTER OF HOLE

LETTERING: HELVETICA & OPT

R 5.5 (24x)

P

18.5

100° (3x)

Q 156.0 ± 0.1
Q 65.0 ± 0.1
Q 50.5 ± 0.1

60° (3x)

ESD SYMBOL
18 x 0.3 mm THICK

Q 13.0 ± 0.2
Q 20.5 ± 0.2

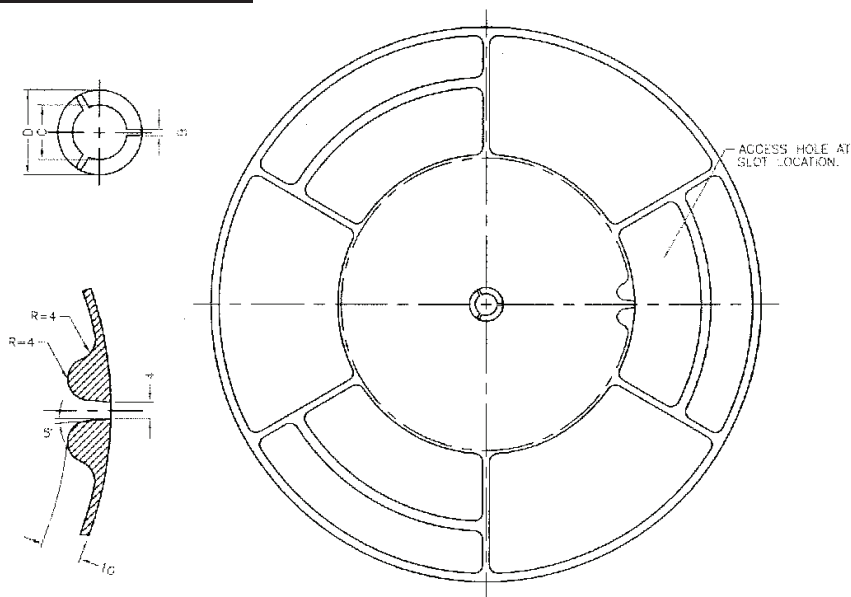
1.9 ± 0.3

120°

DETAIL "X"

Q 18 x 0.3 THICK

13" Reel Drawing (3000pcs/reel)



A	N	W1	W2	W3	D	B	C	Tape Width
330 (13'')	178 (7'') max.	12.4+2/-0	18.4 max.	12.35 min. 15.40 max.	20.2 min.	1.5 min	13.0+0.5/-0.2	12

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